

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XCM517xxxxDR-G
Typical Mass: 9 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.128	Silicon	125300	7440-21-3
	-	Arsenic	7	7440-38-2
Lead pad	2.248	Nickel	249800	7440-02-0
	0.178	Silver	19800	7440-22-4
	0.033	Gold	3600	7440-57-5
Die attach	0.025	Epoxy Resin	2800	—
	0.022	Silica	2500	60676-86-0
Bonding wire	0.278	Gold	30900	7440-57-5
Resin	4.579	Silica	508800	60676-86-0
	0.280	Epoxy Resin	31100	—
	0.229	Phenol Resin	25400	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."